

# **ExaMAX**®





(2.00 mm) .0787"

# ExaMAX® BACKPLANE SYSTEM

#### **Provides** 2.00 mm exceptionally Mates with: **SPECIFICATIONS** column pitch low mating FBTF-RA For complete specifications and recommended PCB layouts see www.samtec.com?EBTM-VT or force while PAM4 maintaining excellent www.samtec.com?EBTM-RA normal force Insulator Material: Liquid Crystal Polymer Contact Material: Copper Alloy Copper Alloy Plating: Sn or Au over 50 µ" (1.27 µm) Ni Operating Temp Range: -55 °C to +105 °C Current Rating: APPLICATION 4.2 A per pin (1 pin powered) Contact Wipe: 2.4 mm RoHS Compliant: Two reliable **RECOGNITIONS** points of contact Press-fit with 2.4 mm wipe For complete scope termination of recognitions see www.samtec.com/quality NO. OF PAIRS COLUMN EBTM **COLUMNS** PER COLUMN **PITCH**

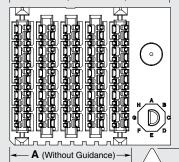
### **ALSO AVAILABLE** (MOQ Required)

· Staging

#### **TOOLING**

• For press-fit extraction and insertion tool options, visit www.samtec.com/tooling

<b>-4</b> = 4 Pairs							
<b>6</b> = 6 Pairs							
C (With Guidance)							





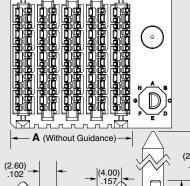


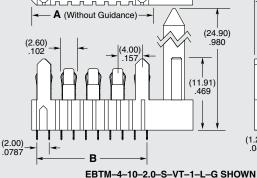
GUIDANCE (EBTM-VT)	KEYING							
	-A	-В	-C	–D	-E	-F	-G	H-
-L /-R		$G = \left( \begin{array}{c} A \\ B \\ C \end{array} \right) = \left( \begin{array}{c} C \\ C \end{array} \right)$		$\bigoplus_{G \in E}^{A} \bigcap_{D}^{G}$				$G = \begin{bmatrix} A & B \\ C & C \end{bmatrix}$

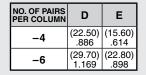
COLUMNS	Α	В	С	
-06	(11.90)	(10.00)	(18.35)	
	.469	.394	.722	
-08	(15.90)	(14.00)	(22.35)	
	.626	.551	.880	
-10	(19.90)	(18.00)	(26.35)	
	.783	.709	1.037	
-12	(23.90)	(22.00)	(30.35)	
	.941	.866	1.195	

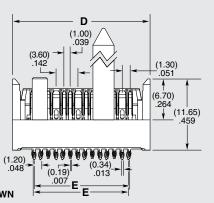
Some lengths, styles and options are non-standard, non-returnable.

ExaMAX® is a registered trademark of AFCI.

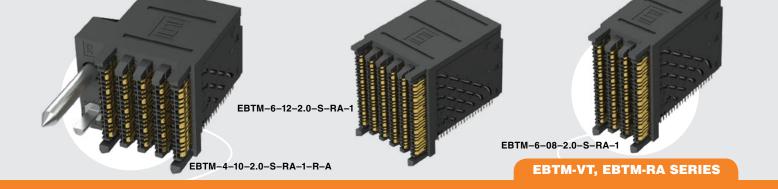


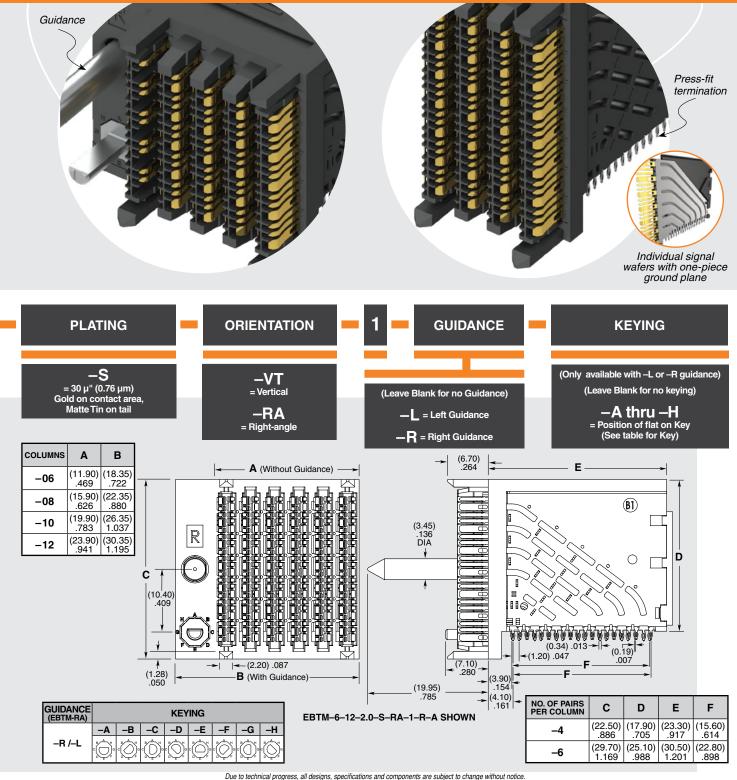






Due to technical progress, all designs, specifications and components are subject to change without notice





## **Mouser Electronics**

**Authorized Distributor** 

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Samtec:

EBTM-4-06-2.0-S-VT-1-R